2815 #6/A

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Cheng-Lien Chiang		
Assignee:	Bridge Semiconductor Corporation		
Title:	SEMICONDUCTOR PACKAGE DEVICE		
Serial No.:	10/042,812	Filed:	January 9, 2002
Examiner:	Chu. C.	Group Art Unit:	2815
Atty. Docket No.:	BDG005		

COMMISSIONER FOR PATENTS
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RESPONSE

In response to the Office Action dated April 23, 2003, please amend the application as follows.

In the Specification

Replace the paragraph at page 10, lines 5-14 with the following paragraph:

A1

FIGS. 1A and **1B** are top and bottom perspective views, respectively, of semiconductor chip 110 which is an integrated circuit in which various transistors, circuits, interconnect lines and the like are formed (not shown). Chip 110 includes opposing major surfaces 112 and 114 and has a thickness of 200 microns between these surfaces. Surface 112 is an upper surface, and surface 114 is a lower surface. Surface 112 is the active surface and includes conductive pads 116 arranged in a single row and passivation layer 118. Pads 116 are substantially aligned with passivation layer 118 so that surface 112 is essentially flat. Alternatively, if desired, pads 116 can extend above or be recessed below passivation layer 118. Pads 116 provide bonding sites to